



Material Content Data Sheet



Sales Product Name		IPL60R299CP		Issued		20. July 2018		
MA#		MA001394884						
Package		PG-VSON-4-1		Weight*		189.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.215	3.29	3.29	32870	32870
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		67	
	non noble metal	zinc	7440-66-6	0.051	0.03		269	
	non noble metal	iron	7439-89-6	1.017	0.54		5380	
wire	non noble metal	copper	7440-50-8	41.300	21.84	22.42	218439	224155
	non noble metal	copper	7440-50-8	0.723	0.38	0.38	3824	3824
	encapsulation	organic material	carbon black	1333-86-4	0.215	0.11		1135
plastics	plastics	epoxy resin	-	11.053	5.85		58462	
	inorganic material	silicondioxide	60676-86-0	96.047	50.80	56.76	507997	567594
leadfinish	non noble metal	tin	7440-31-5	2.397	1.27	1.27	12680	12680
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1333	1333
solder	noble metal	silver	7440-22-4	0.118	0.06		625	
	non noble metal	tin	7440-31-5	0.095	0.05		500	
	non noble metal	lead	7439-92-1	4.518	2.39	2.50	23893	25018
heatspreader	inorganic material	phosphorus	7723-14-0	0.008	0.00		40	
	non noble metal	zinc	7440-66-6	0.030	0.02		159	
	non noble metal	iron	7439-89-6	0.601	0.32		3181	
	non noble metal	copper	7440-50-8	24.418	12.91	13.25	129146	132526
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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